

Octal-Bus Transceiver/Registers, 3-State

CD54/74AC/ACT646 - Non-Inverting CD54/74AC/ACT648 - Inverting

Type Features:

- Buffered inputs
- Typical propagation delay: 5.3 ns @ V_{CC} = 5 V, T_A = 25° C, C_L = 50 pF

The RCA CD54/74AC646 and CD54/74AC648 and the CD54/74ACT646 and CD54/74ACT648 3-state, octal-bus transceiver/registers use the RCA ADVANCED CMOS technology. The CD54/74AC648 and CD54/74ACT648 have inverting outputs. The CD54/74AC646 and CD54/74ACT646 have non-inverting outputs. These devices are bus transceivers with D-type flip-flops which act as internal storage registers on the LOW-to-HIGH transition of either CAB or CBA clock inputs. Output Enable (OE) and Direction (DIR) inputs control the transceiver functions. Data present at the high-impedance output can be stored in either register or both but only one of the two buses can be enabled as outputs at any one time. The Select controls (SAB and SBA) can multiplex stored and transparent (real time) data. The Direction control determines which data bus will receive data when the Output Enable (OE) is LOW. In the highimpedance mode (Output Enable HIGH), A data can be stored in one register and B data can be stored in the other register. The clocks are not gated with the Direction (DIR) and Output Enable (OE) terminals; data at the A or B terminals can be clocked into the storage flip-flops at any time.

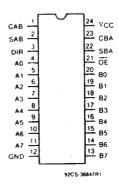
The CD74AC/ACT646 and CD74AC/ACT648 are supplied in 24-lead dual-in-line narrow-body plastic packages (EN suffix) and in 24-lead dual-in-line small-outline plastic packages (M suffix). Both package types are operable over the following temperature ranges: Commercial (0 to 70°C); Industrial (-40 to +85°C); and Extended Industrial/Military (-55 o +125°C).

The CD54AC/ACT646 and CD54AC/ACT648, available in chip form (H suffix), are operable over the -55 to +125°C temperature range.

Family Features:

- Exceeds 2-kV ESD Protection MIL-STD-883, Method 3015
- SCR-Latchup-resistant CMOS process and circuit design
- Speed of bipolar FAST*/AS/S with significantly reduced power consumption
- Balanced propagation delays
- AC types feature 1.5-V to 5.5-V operation and balanced noise immunity at 30% of the supply
- ± 24-mA output drive current
 - Fanout to 15 FAST* ICs
 - Drives 50-ohm transmission lines

*FAST is a Registered Trademark of Fairchild Semiconductor Corp.



TERMINAL ASSIGNMENT

FUNCTION TABLE

	INPUTS					DATA	1/0#	OPERATION OR FUNCTION			
ŌĒ	DIR	CAB	CBA	SAB	SBA	A0 THRU A7	BO THRU B7	646	648		
X	X	X	· x	X	×	Input Not specified	Not specified Input	Store A, B unspecified Store B, A unspecified	Store A, B unspecified Store B, A unspecified		
HH	X	∴/¯ H or L	_/ H or L	X .	X	Input	Input	Store A and B Data Isolation, hold storage	Store A and B Data Isolation, hold storage		
L	L	X	X H or L	X	H	Output	Input	Real-Time B Data to A Bus Stored B Data to A Bus	Real-Time B Data to A Bus Stored B Data to A Bus		
LL	H H	X H or L	X	L H	X	Input	Output	Real-Time A Data to B Bus Stored A Data to B Bus	Real-Time A Data to B Bus Stored A Data to B Bus		

#The data output functions may be enabled or disabled by various signals at the $\overline{\text{OE}}$ and DIR inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every low-to-high transition on the clock inputs. To prevent excess currents in the High-Z modes, all I/O terminals should be terminated with 10 k Ω resistors.

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE (V_{∞})
DC INPUT DIODE CURRENT, I_{iK} (for $V_1 < -0.5$ V or $V_1 > V_{CC} + 0.5$ V)
DC OUTPUT DIODE CURRENT, I_{OK} (for $V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V)
DC OUTPUT SOURCE OR SINK CURRENT per Output Pin, I _o (for $V_0 > -0.5 \text{ V}$ or $V_0 < V_{CC} + 0.5 \text{ V}$) $\pm 50 \text{ mA}$
DC V _{CC} or GROUND CURRENT (I _{CC} or I _{GND})
POWER DISSIPATION PER PACKAGE (PD):
For $T_A = -55$ to +100°C (PACKAGE TYPE E)
For T _A = +100 to +125°C (PACKAGE TYPE E) Derate Linearly at 8 mW/°C to 300 mW
For $T_A = -55$ to $+70$ °C (PACKAGE TYPE M)
For T _A = +70 to +125°C (PACKAGE TYPE M)
OPERATING-TEMPERATURE RANGE (T _A)
STORAGE TEMPERATURE (Tsig)65 to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
At distance 1/16 \pm 1/32 in. (1.59 \pm 0.79 mm) from case for 10 s maximum
Unit inserted into PC board min. thickness 1/16 in. (1.59 mm) with solder contacting lead tips only +300°C
*For up to 4 outputs per device; add ± 25 mA for each additional output.

RECOMMENDED OPERATING CONDITIONS:

For maximum reliability, normal operating conditions should be selected so that operation is always within the following ranges:

OLIA DA OTERIOTIOS	LIN	IITS		
CHARACTERISTICS	MIN.	MAX.	UNITS	
Supply-Voltage Range, Vcc*:				
(For T _A = Full Package-Temperature Range)				
AC Types	1.5	5.5	V	
ACT Types	4.5	5.5	V	
DC Input or Output Voltage, V _I , V _O	0	Vcc	V	
Operating Temperature, T _A	-55	+125	°C	
Input Rise and Fall Slew Rate, dt/dv				
at 1.5 V to 3 V (AC Types)	0	50	ns/V	
at 3.6 V to 5.5 V (AC Types)	0	20	ns/V	
at 4.5 V to 5.5 V (ACT Types)	0	10	ns/V	

^{*}Unless otherwise specified, all voltages are referenced to ground.

Technical Data _

CD54/74AC646, CD54/74AC648 CD54/74ACT646, CD54/74ACT648

STATIC ELECTRICAL CHARACTERISTICS: AC Series

					AMBIENT TEMPERATURE (TA) - °C						
CHARACTERISTI	ics	TEST CON	IDITIONS	V _{cc}	+2	25	-40 to	+85	-55 to	+125	UNITS
		V, (V)	I _o (mA)	(V)	MIN.	MAX.	MIN.	MAX:	MIN.	MAX.	
High-Level Input Voltage	V _{IH}		<i>y</i>	1.5 3 5.5	1.2 2.1 3.85	_ 	1.2 2.1 3.85		1.2 2.1 3.85	 	v
Low-Level Input Voltage	VIL			1.5 3 5.5		0.3 0.9 1.65		0.3 0.9 1.65	_ 	0.3 0.9 1.65	V
High-Level Output			-0.05	1.5	1.4	_	1.4		1.4		
Voltage	VoH	V _{IH}	-0.05	3	2.9		2.9		2.9		1
		or	-0.05	4.5	4.4		4.4	· -	4.4		
		VIL	-4	3	2.58	_	2.48		2.4) v
			-24	4.5	3.94		3.8	<u>`</u>	3,7		1
		#, * {	-75	5.5	-		3.85	_	_		1
		" ' \{	-50	5.5			_	9_	3.85		
Low-Level Output			0.05	1.5		0.1	4-35	0.1		0.1	1
Voltage	Vol	ViH	0.05	3		0.1	30	0.1		0.1	1
		or	0.05	4.5	- 00	0.1		0.1	1-	0.1	
		ViL	12	3		0.36	$(I_T)_{i,j}$	0.44		0.5	V
			24	4.5	<u></u>	0.36		0.44		0.5	
		#, * {	75	5.5	1	-		1.65			1
			50	5.5	9					1.65	
Input Leakage Current	t,	V _{cc} or GND		5.5		±0.1		±1	_	±1	μΑ
3-State Leakage Current	loz	V _{IM} Of V _{IL} V _O = V _{CC} Of GND		5.5		±0.5		±5	_	±10	μΑ
Quiescent Supply Current, MSI	lcc	V _{cc} or GND	0	5.5	_	8	-	80	_	160	μΑ

[#]Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.
*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

STATIC ELECTRICAL CHARACTERISTICS: ACT Series

						AMBIEN	Т ТЕМРЕ	RATURE	(T _A) - °(<u> </u>		
CHARACTERISTIC	S	TEST CO	NDITIONS	V _{cc}	+25		-40 to +85		-55 to +125		UNITS	
		V ₁ (V)	I _o (mA)	(V)	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
High-Level Input Voltage	ViH			4.5 to 5.5	2		2	_	2		V	
Low-Level Input Voltage	VıL	·		4.5 to 5.5		0.8	_	0.8		0.8	V	
High-Level Output		V _{IH}	-0.05	4.5	4.4		4.4	_	4.4	_		
Voltage	V _{OH}	or V _{IL}	-24	4.5	3.94	_	3.8	—	3.7	_		
			#, * {	-75	5.5		_	3.85	_	_	_]
		<i>""</i>	-50	5.5					3.85			
Low-Level Output		Viн	0.05	4.5	-	0.1	<u> </u>	0.1	–	.0.1		
Voltage	Vol	or V _{IL}	24	4.5	_	0.36		0.44	_	0.5	lvl	
		#, * {	- 75	5.5	_	_		1.65	, —	_		
		" ")	50	5.5	_	-4.	JG_//		_	1.65]	
Input Leakage Current	l,	V _{cc} or GND		5.5	36 2	±0.1	I.C	±1	_	±1	μΑ	
3-State Leakage Current	łoż	VIH Or VIL Vo= Vcc Or GND		5.5	- (±0.5		±5	_	±10	μΑ	
Quiescent Supply Current, MSI	lcc	V _{cc} or GND	0	5.5	_	8		80		160	μΑ	
Additional Quiescent St Current per Input Pin TTL Inputs High 1 Unit Load	upply ΔI _{cc}	V _{cc} -2.1		4.5 to 5.5	_	2.4	_	2.8	_	3	mA	

[#]Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize

ACT INPUT LOADING TABLE

INPUT	UNIT LOAD*
CAB, CBA	1.25
SAB, SBA	1.2
DIR	0.67
ŌĒ	1.17
An, Bn	0.4

*Unit load is ΔI_{CC} limit specified in Static Characteristics Chart, e.g., 2.4 mA max. @ 25° C.

power dissipation.
*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

PREREQUISITE FOR SWITCHING: AC Series

:			AMBI	A) - °C			
CHARACTERISTICS	SYMBOL	V _{cc} (V)	-40 to +85		-55 to +125		UNITS
OHAHAOT EMOTION			MIN.	MAX.	MIN.	MAX.	
Max. Frequency	fmax	1.5 3.3* 5†	11 101 143		10 89 125		MHz
Setup Time Data to Clock	tsu	1.5 3.3 5	27 3.1 2.2		31 3.5 2.5	=	ns
Hold Time Data to Clock	t _H	1.5 3.3 5	2 2 2	=	2 2 2		ns
Clock Pulse Width	tw	1.5 3.3 5	44 4.9 3.5	=	50 5.6 4	_	ns

*3.3 V: min. is @ 3 V †5 V: min is @ 4.5 V

SWITCHING CHARACTERISTICS: AC Series; tr, tr = 3 ns, CL = 50 pF

		l	AMBIE				
014040750107100	SYMBOL	V _{cc}	-40 to			+125	UNITS
CHARACTERISTICS	STMBOL	(V)	MIN.	MAX.	/ ^D MIN.	MAX.	
Propagation Delays: Store A Data to B Bus Store B Data to A Bus	t _{PLH}	1.5 3.3*	4.8	154 17.1	C 12 4.7	169 18.9	ns
646	t _{PHL}	5†	3.5	12.3	3.4	13.5	
Store Ā Data to B Bus Store B Data to A Bus 648	t _{PLH} t _{PHL}	1.5 3.3 5	4.8 3.5	154 17.1 12.3	4.7 3.4	169 18.9 13.5	ns
A Data to B Bus B Data to A Bus 646	telн tehl	1.5 3.3 5	4 2.8	125 14 10	3.9 2.8	138 15.4 11	ns
Ā Data to B Bus B Data to A Bus 648	telh tehl	1.5 3.3 5	4 2.8	125 14 10	3.9 2.8	138 15.4 11	ns
Select to Data 646	t _{PLH} t _{PHL}	1.5 3.3 5	4.3 3.1	136 15.3 10.9	4.2 3	150 16.8 12	ns
Select to Data 648	tегн tенг	1.5 3.3 5	4.3 3.1	136 15.3 10.9	4.2 3	150 16.8 12	ns
3-State Enabling/ Disabling Time Bus to Output or Register to Output	tezi tezh telz tenz	1.5 3.3 5	 5.2 3.5	154 18.4 12.3	5.1 3.4	169 20.2 13.5	ns
Power Dissipation Capacitance	C _{PD} §		150	Тур.	150	Тур.	pF
Min. (Valley) V During Switching of Other Outputs (Output Under Test Not Switching)	V _{ону} See Fig. 1	5		4 Тур.	@ 25°C		V
	Vole See Fig. 1	5		1 Тур.	@ 25°C		V
Input Capacitance	Cı		_	10	_	10	pF
3-State Output Capacitance	Co		_	15		15	pF

*3.3 V: min. is @ 3.6 V max. is @ 3 V

†5 V: min. is @ 5.5 V max. is @ 4.5 V $V_{CC} = supply voltage.$

PREREQUISITE FOR SWITCHING: ACT Series

		V _{cc} (V)	AMBI				
CHARACTERISTICS Max. Frequency Setup Time Data to Clock	SYMBOL		-40 to +85		-55 to +125		UNITS
	· ·		MIN.	MAX.	MIN.	MAX.]
Max. Frequency	f _{max}	5*	125	— ,	110	_	MHz
Setup Time Data to Clock	t _{su}	5	2.2	_	2.5	_	ns
Hold Time Data to Clock	tн	5	2	_	. 2	_	ns
Clock Pulse Width	tw	5	3.9	_	4.5	_	ns

^{*5} V: min. is @ 4.5 V

SWITCHING CHARACTERISTICS: ACT Series; t, t, = 3 ns, CL = 50 pF

			AMBIE				
CHARACTERISTICS	SYMBOL	V _{cc}	-40 to	-40 to +85		-55 to +125	
		(V)	MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Store A Data to B Bus Store B Data to A Bus 646	tегн tенг	5*	4	14.1	3.9	15.5	ns
Store Ā Data to B Bus Store B Data to A Bus 648	t _{PLH} t _{PHL}	5	34	14.1	3.9	15.5	ns
A Data to B Bus B Data to A Bus 646	t _{PLH} t _{PHL}	5	3.2	11.4	3.1	12.5	ns
Ā Data to B Bus B Data to A Bus 648	t _{PLH} t _{PHL}	5	3.2	11.4	3.1	· 12.5	ns
Select to Data 646	t _{PLH} t _{PHL}	5	3.7	13.2	3,6	14.5	ns
Select to Data 648	t _{PLH} t _{PHL}	5	4	14.1	3.9	15.5	ns
3-State Enabling/ Disabling Time Bus to Output or Register to Output	tezi. tezh telz tenz	5	4	14,1	3.9	15.5	ns
Power Dissipation Capacitance	C _{PD} §	_	150	Тур.	150	Тур.	ρF
Min. (Valley) Vo During Switching of Other Outputs (Output Under Test Not Switching)	Vонv See Fig. 1	5		4 Typ. (@ 25°C	150 Typ.	
Max. (Peak) Vo During Switching of Other Outputs (Output Under Test Not Switching) Vo	Vole See Fig. 1	5		1 Тур. (@ 25°C		V
Input Capacitance	Cı	_		10		10	pF
3-State Output Capacitance	Co	_		15		15	ρF

¹⁵ V: min. is @ 5.5 V max. is @ 4.5 V

§C_{PD} is used to determine the dynamic power consumption, per package. $P_D = C_{PD}V_{CC}^2 f_i + \Sigma (C_LV_{CC}^2 f_o) + V_{CC}\Delta I_{CC}$ where $f_i = input frequency$

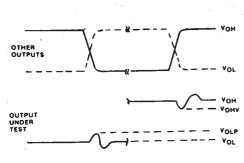
 $f_o = output frequency$

 C_L = output load capacitance V_{CC} = supply voltage.

Technical Data

CD54/74AC646, CD54/74AC648 CD54/74ACT646, CD54/74ACT648

PARAMETER MEASUREMENT INFORMATION



- NOTES:

 1. VOMY AND VOLP ARE MEASURED WITH RESPECT TO A GROUND REFERENCE NEAR THE OUTPUT UNDER TEST.

 2. INPUT PULSES HAVE THE FOLLOWING CHARACTERISTICS: PRR :: 1 MHz, t, -3 ms, t; -3 ms, SKEW 1 ms.

 3. R.F. FIXTURE WITH 700-MHz DESIGN RULES REQUIRED.

 IC SHOULD BE SOLDERED INTO TEST BOARD AND BYPASSED WITH 0.1 pF CAPACITOR. SCOPE AND PROBES REQUIRE 700-MHz BANDWIDTH.

 92CS-42406

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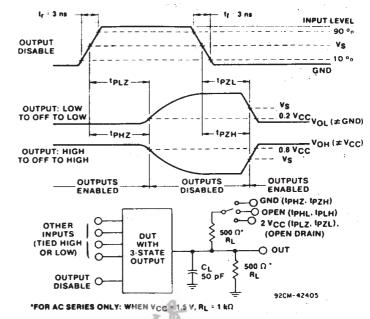


Fig. 2 - Three-state propagation delay waveforms and test circuit.



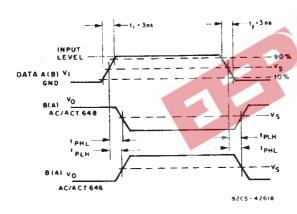


Fig. 3 - Propagation delay times.

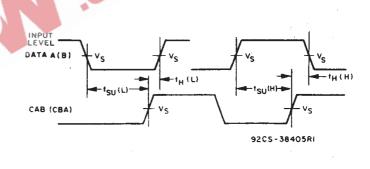


Fig. 4 - Data setup and hold times.

OUTPUT
DUT 500 M CL DUTPUT 50 pF
*FOR AC SERIES ONLY: WHEN
V _{CC} = 1.5 V, R _L = 1 kΩ
92CS - 42309

92C\$	-	47	30	Ģ
92C\$	-	41	20	•

	CD54/74AC	CD54/74ACT
Input Level	V _{cc}	3 V
Input Switching Voltage, Vs	0.5 V _{CC}	1.5 V
Output Switching Voltage, Vs	0.5 V _{cc}	0.5 V _{CC}

Fig. 5 - Test circuit.

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